

## Description

### N-channel Enhancement Mode Power MOSFET

#### Features

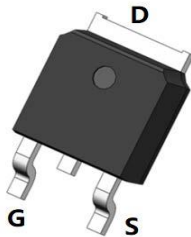
- 30V, 150A  
 $R_{DS(ON)}$  Typ=2.5m $\Omega$  @  $V_{GS}$  = 10V  
 $R_{DS(ON)}$  Typ=3.6m $\Omega$  @  $V_{GS}$  = 4.5V
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge

#### Applications

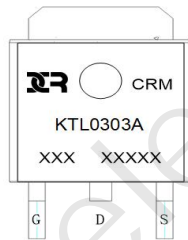
- Load Switch
- PWM Application
- Power Management



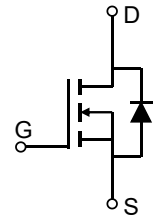
100% UIS TESTED!  
100%  $\Delta V_{ds}$  TESTED!



TO-252-3L



Marking and Pin Assignment



Schematic Diagram

### Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
CRMKTL0303A	CRMKTL0303A	TAPING	TO-252-3L	13"	2500	25000

### Absolute Maximum Ratings (@ $T_C$ = 25°C unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	30	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	600	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	196	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.0	$^\circ\text{C/W}$
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
On Characteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.0	1.6	2.2	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	2.5	3.3	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A	-	3.6	4.7	mΩ
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 15V, f = 1MHz	-	3800	-	pF
C <sub>oss</sub>	Output Capacitance		-	441	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	329	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 10V V <sub>DS</sub> = 15V, I <sub>D</sub> = 15A	-	67	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	11	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	19	-	nC
Switching Characteristics						
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 15V I <sub>D</sub> = 30A, R <sub>GEN</sub> = 3Ω	-	10	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	19	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	50	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	20	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	150	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	600	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I <sub>F</sub> = 20A, di/dt = 100A/us	-	18	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	6	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2. E<sub>AS</sub> condition: Starting  $T_J=25^\circ\text{C}$ ,  $V_{DD}=15\text{V}$ ,  $V_G=10\text{V}$ ,  $R_G=25\text{ohm}$ ,  $L=0.5\text{mH}$ ,  $I_{AS}=28\text{A}$
  3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$ .

## Test Circuit

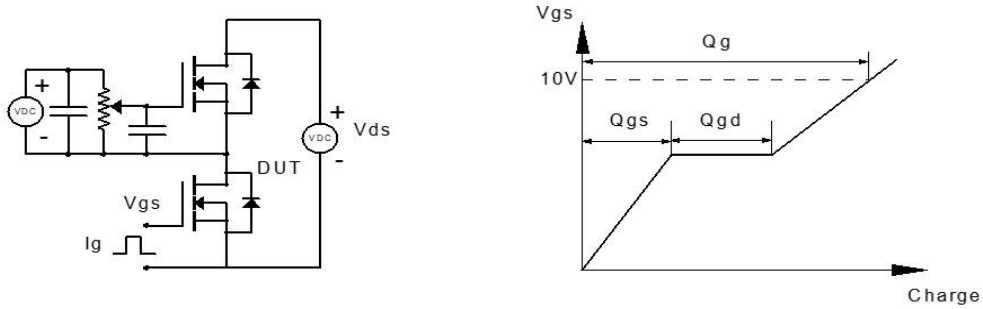


Figure 1: Gate Charge Test Circuit & Waveform

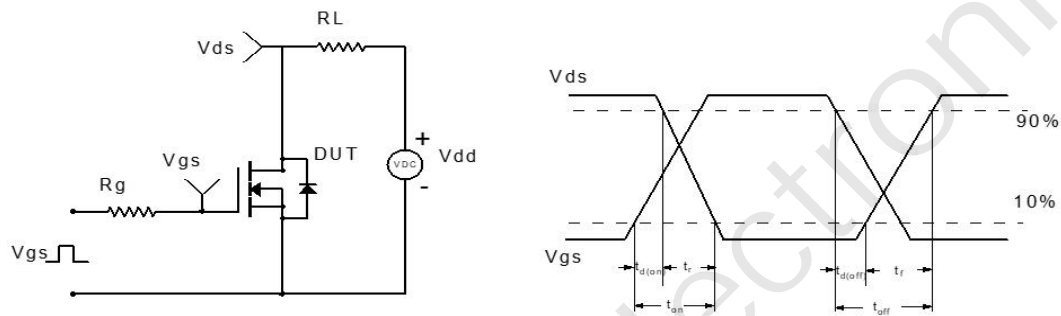


Figure 2: Resistive Switching Test Circuit & Waveform

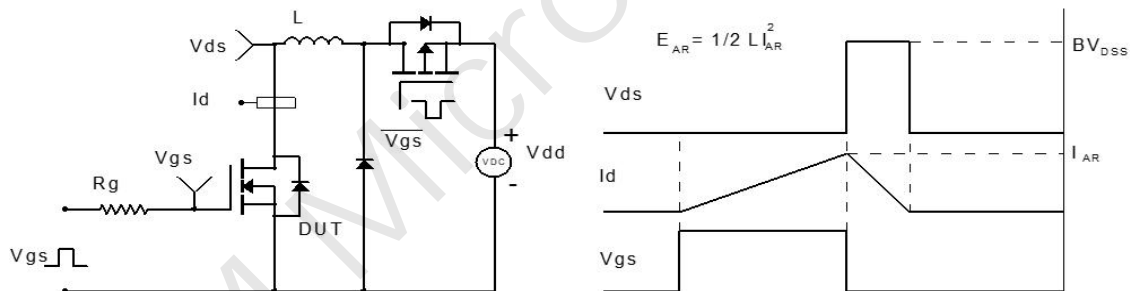


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

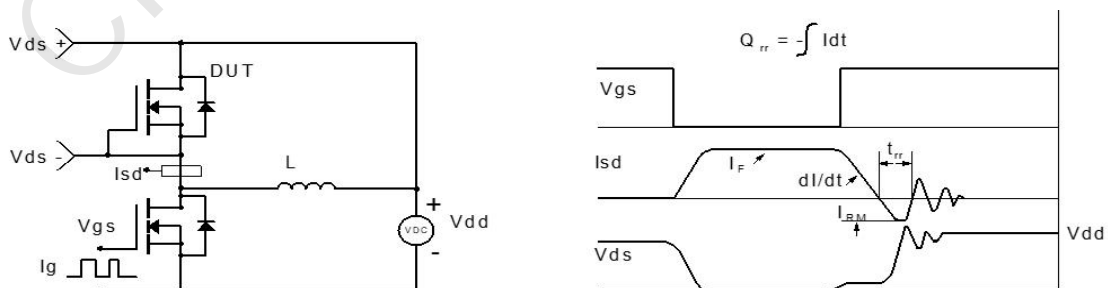
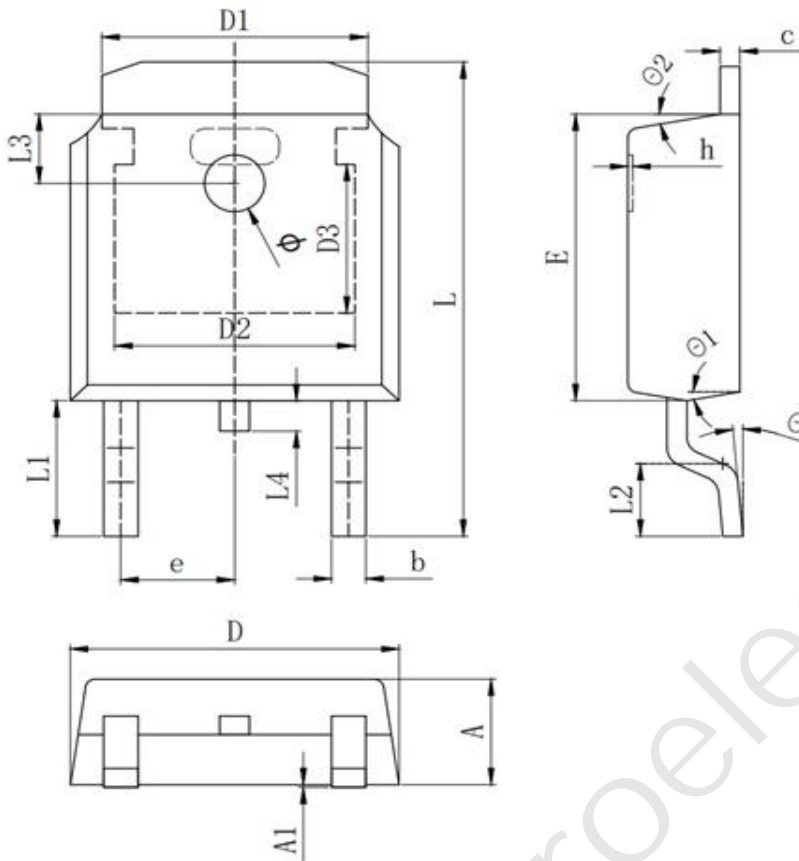


Figure 4: Diode Recovery Test Circuit & Waveform

## Package Mechanical Data(TO-252-3L)



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c (电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
ϕ	1.100	1.200	1.300
θ	0°		8°
θ1	9° TYP		
θ2	9° TYP		

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